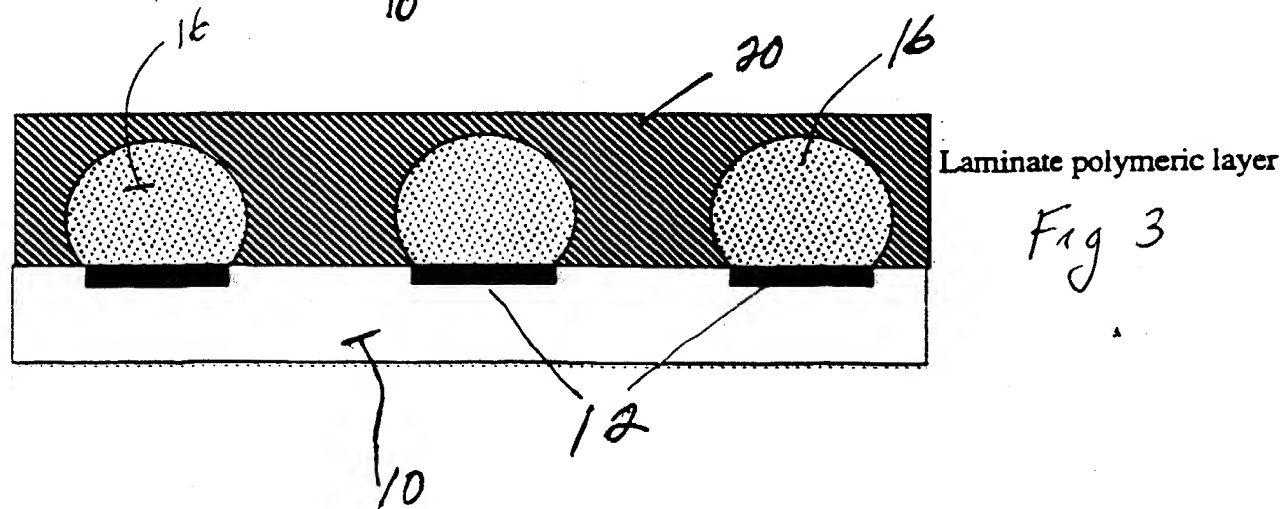
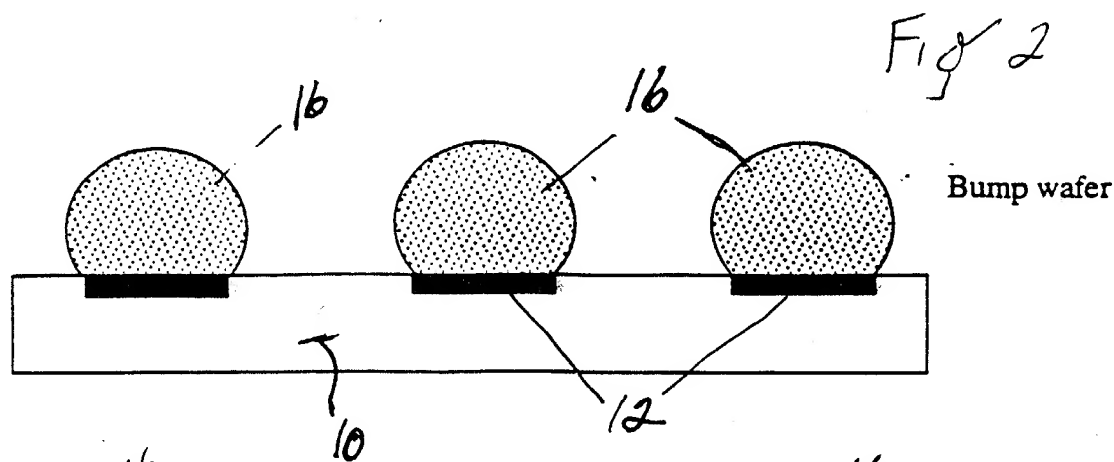
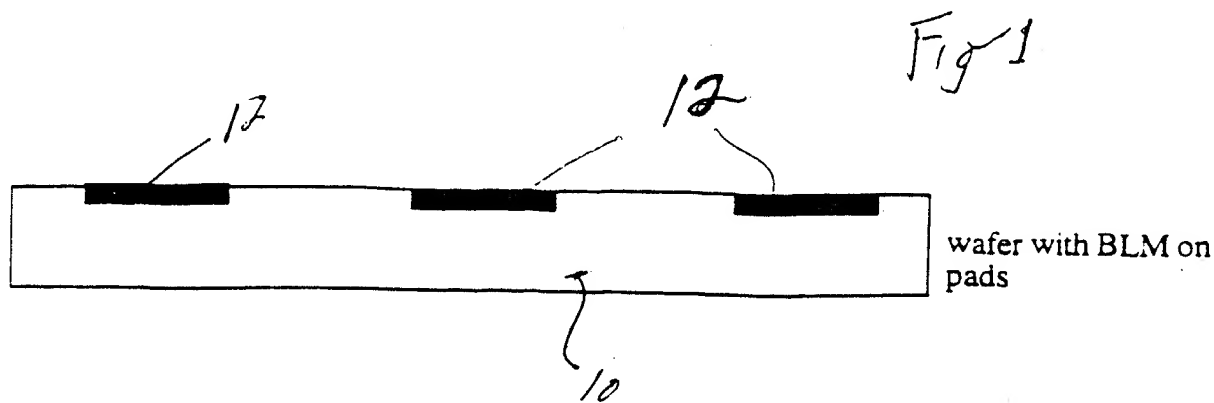


FIG. 1



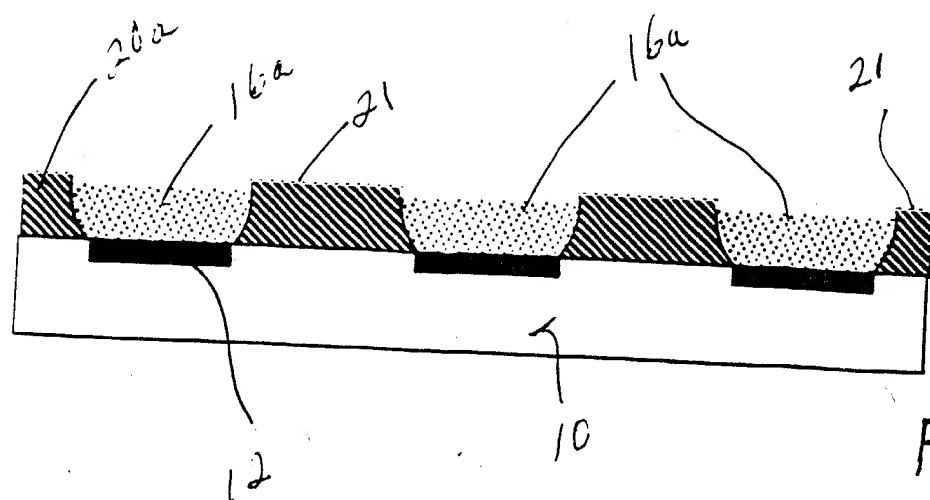


Fig 4A.

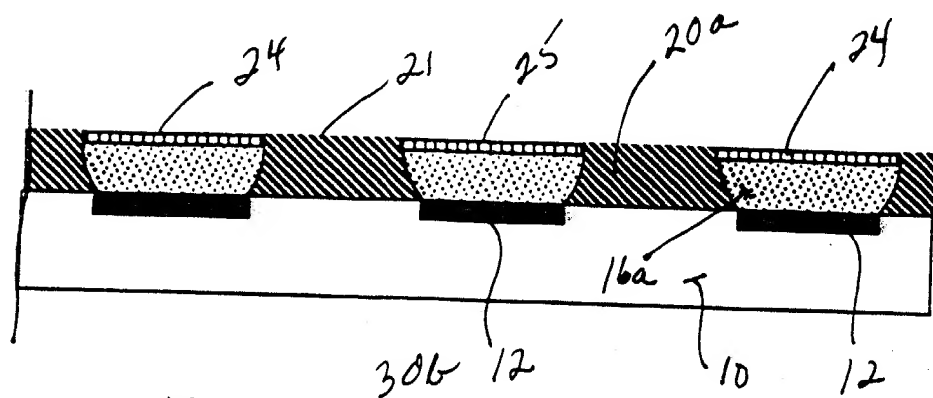


Fig 5A

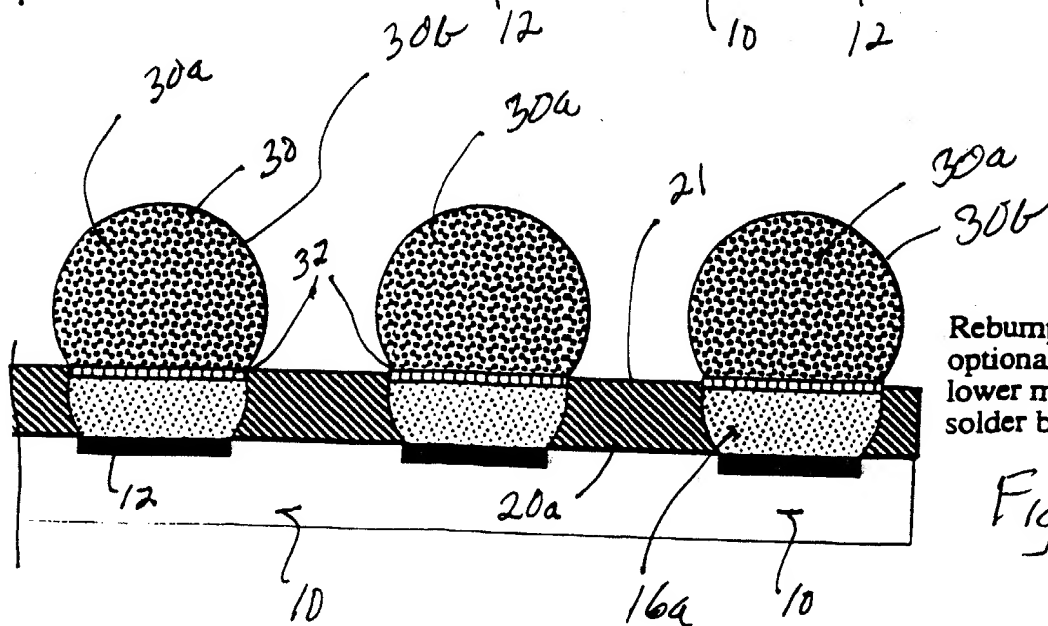
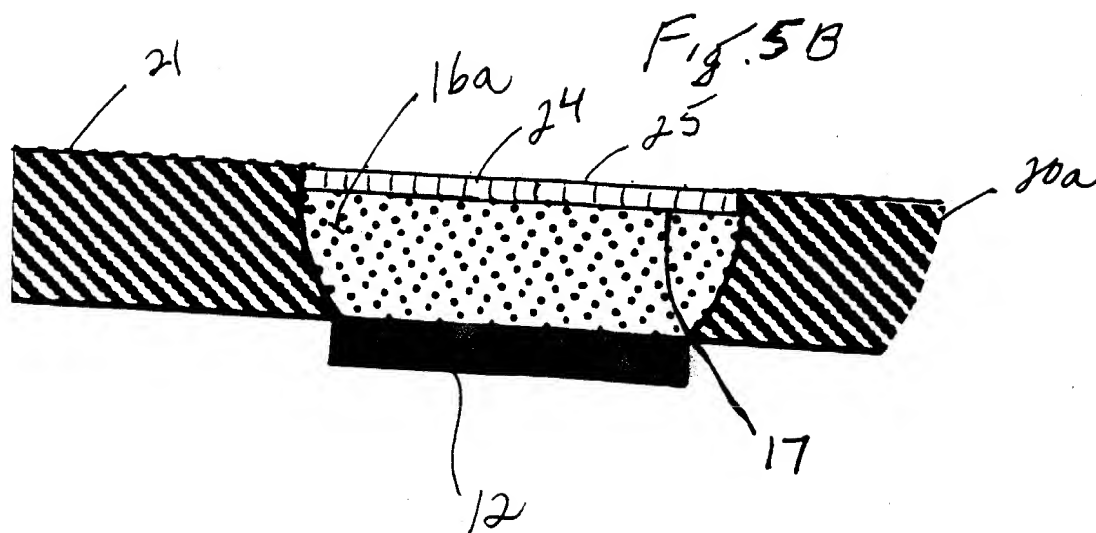
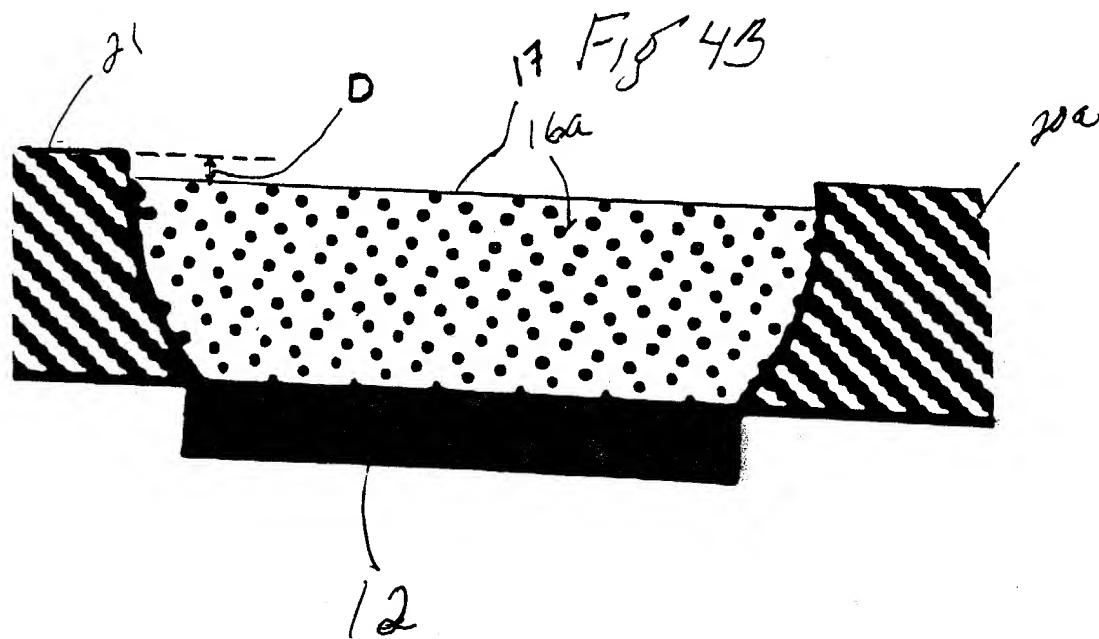
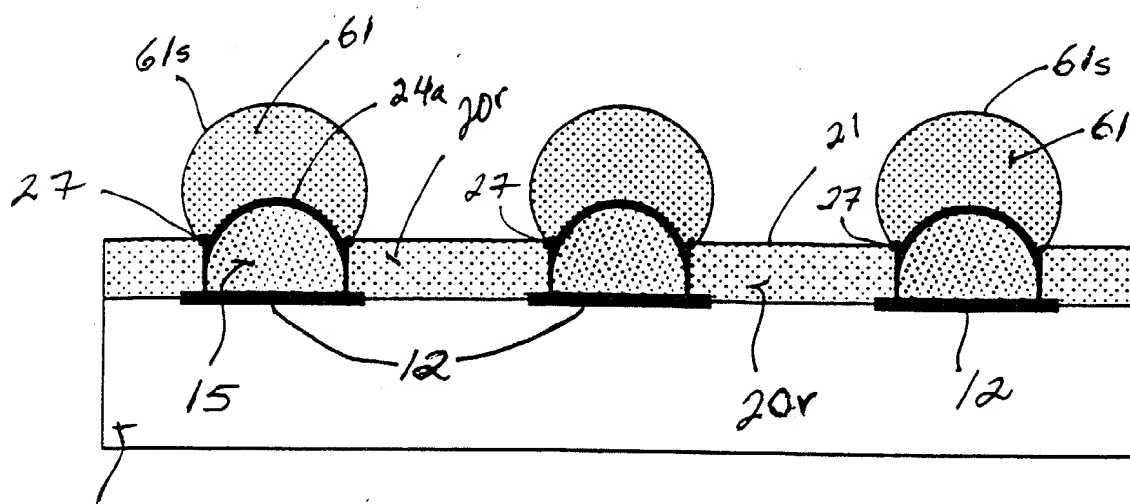


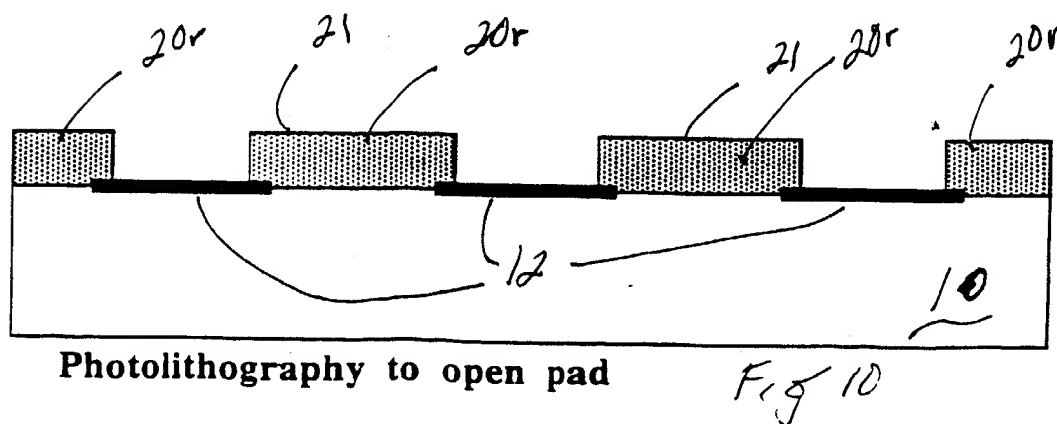
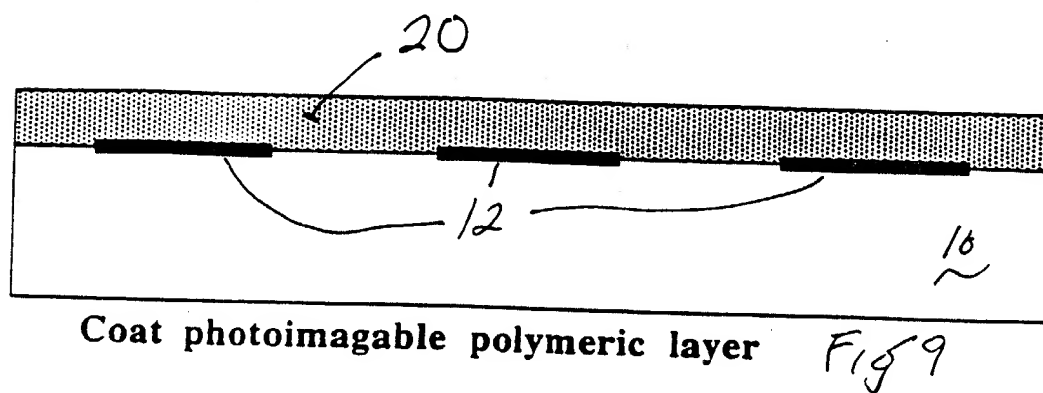
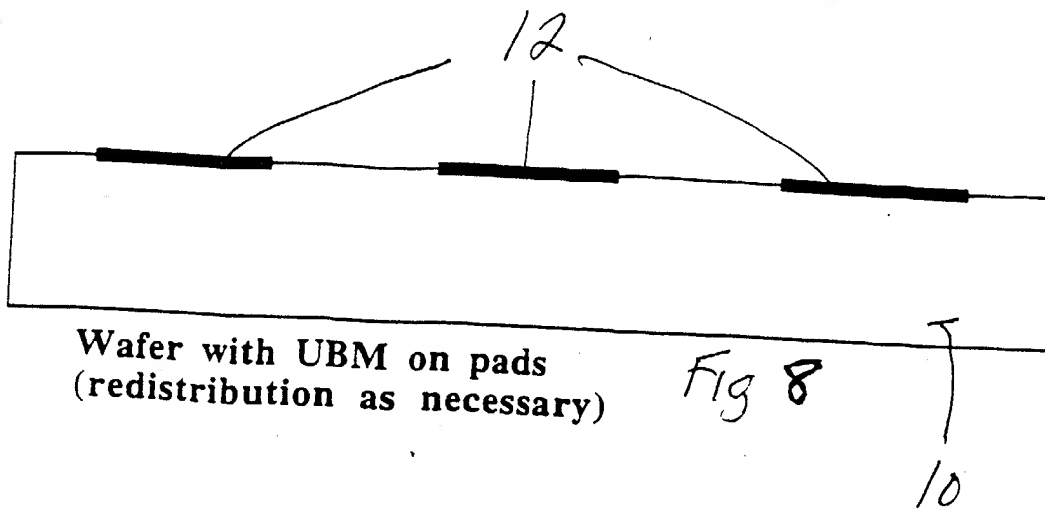
Fig 6

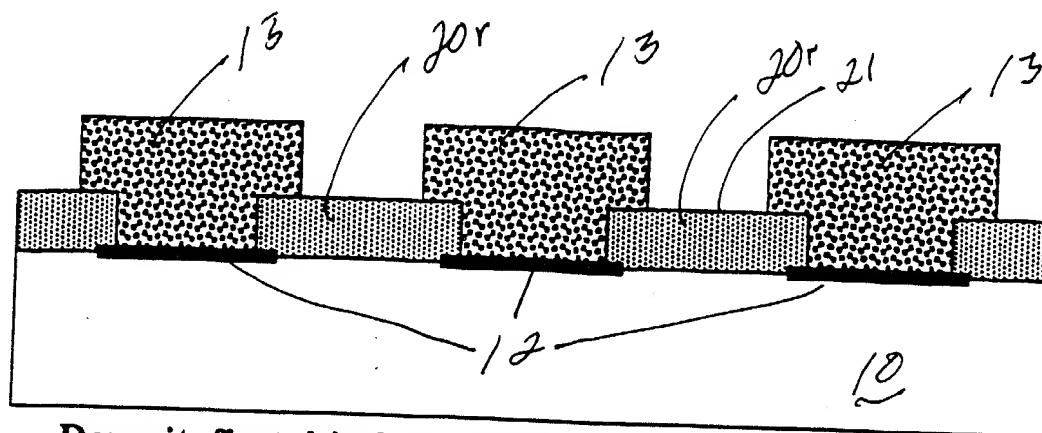




- A wafer bumping structure

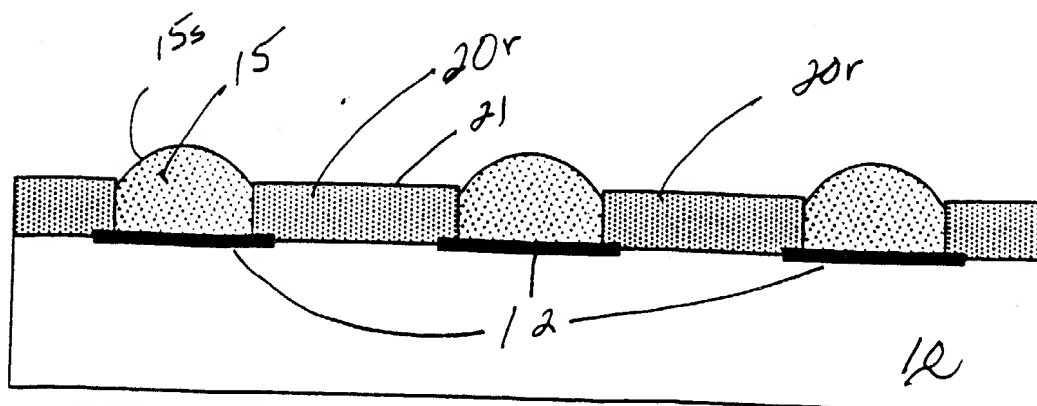
Fig 7





Deposit first kind of solder paste

Fig 11



Reflow wafer to form solder bump
Clean flux residual

Fig 12A

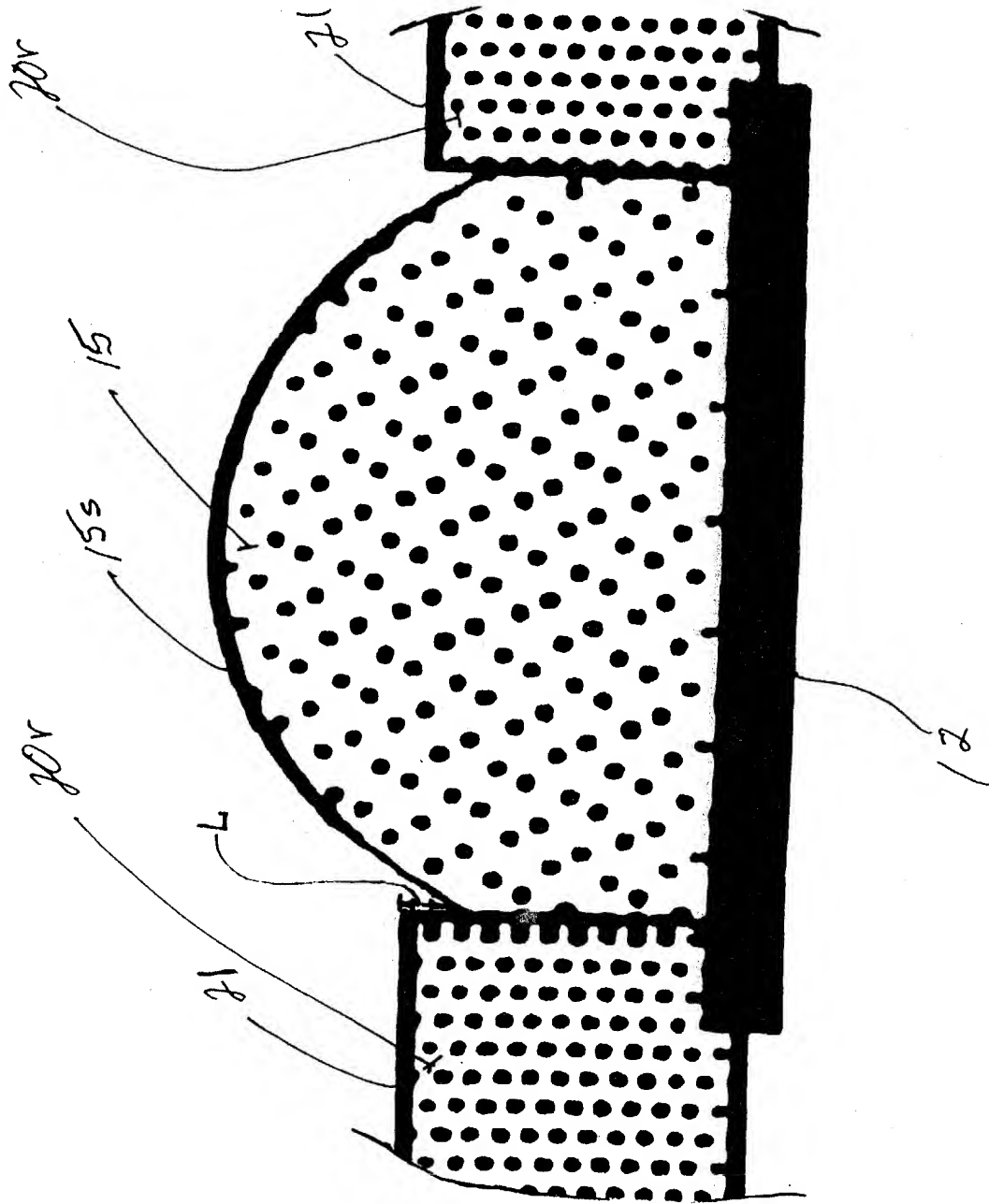


Fig 12B

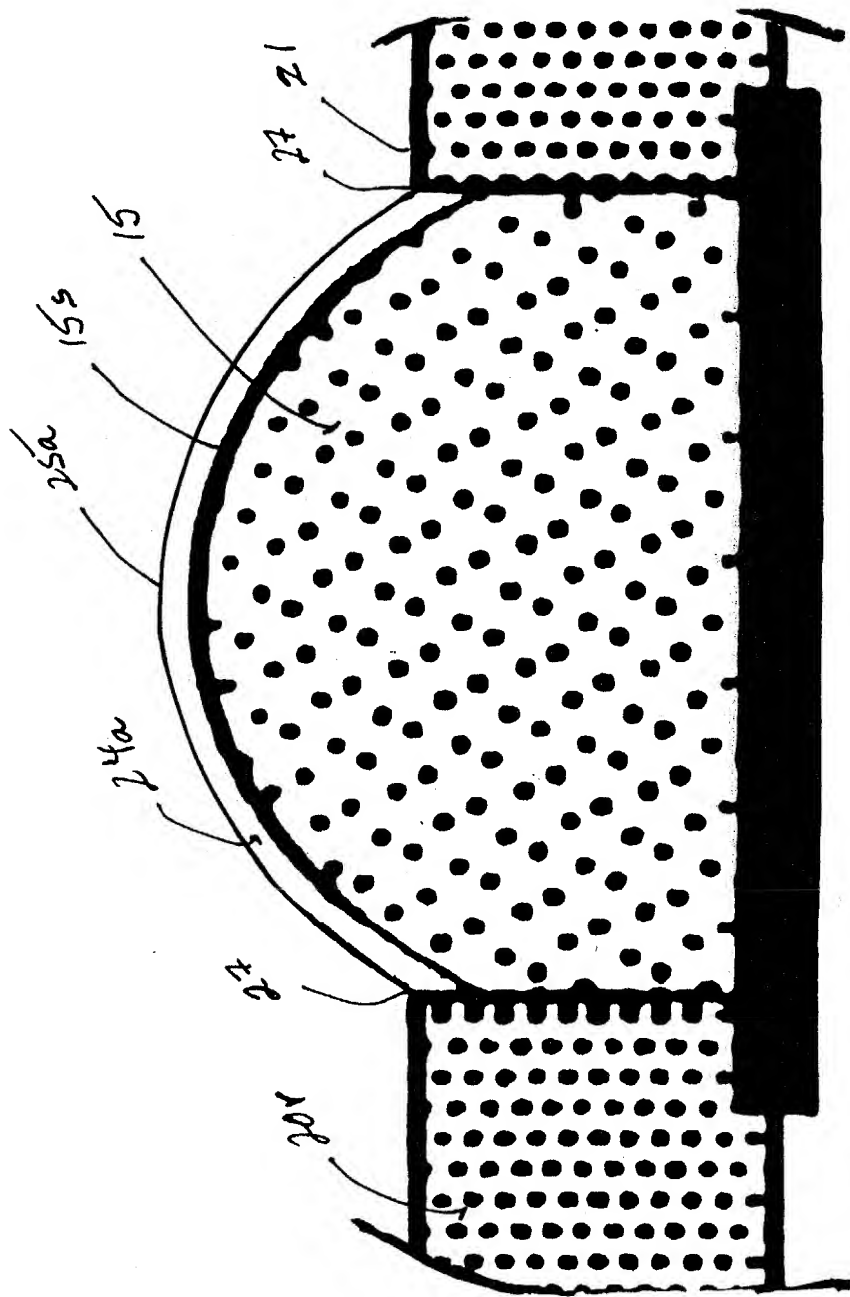
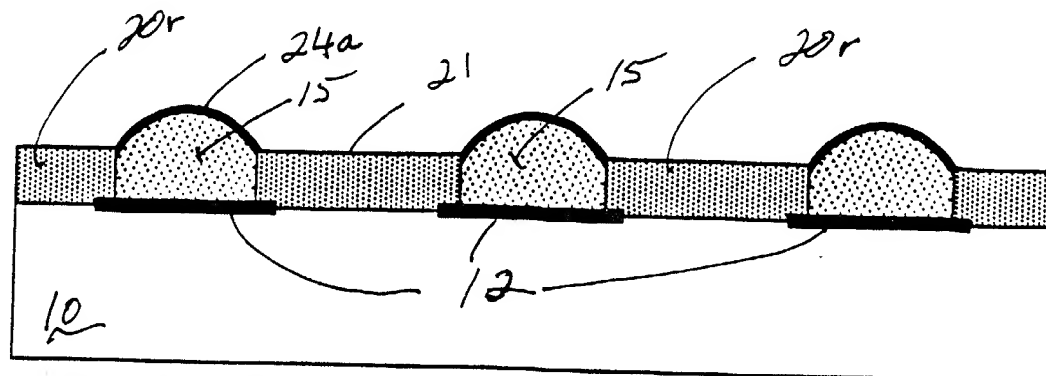
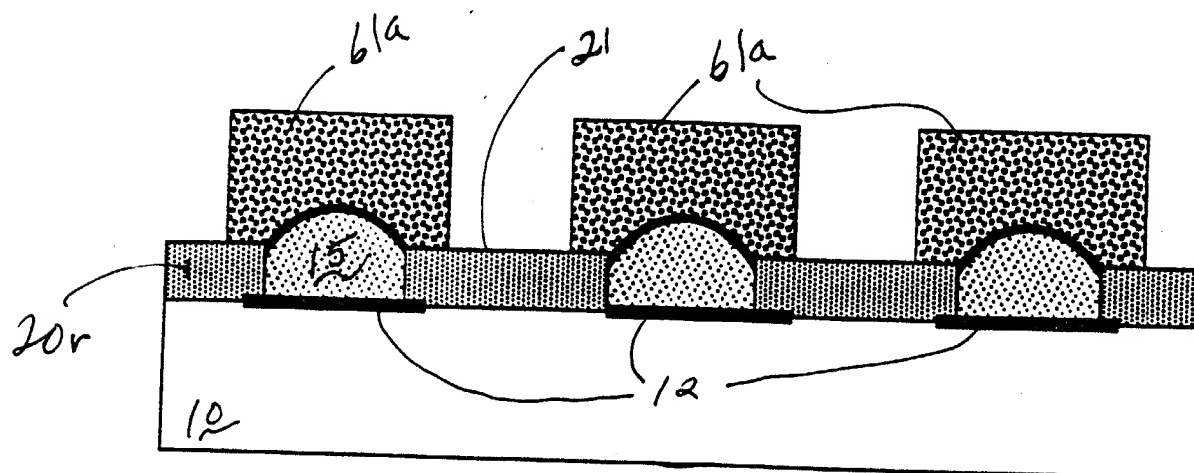


Fig 12C



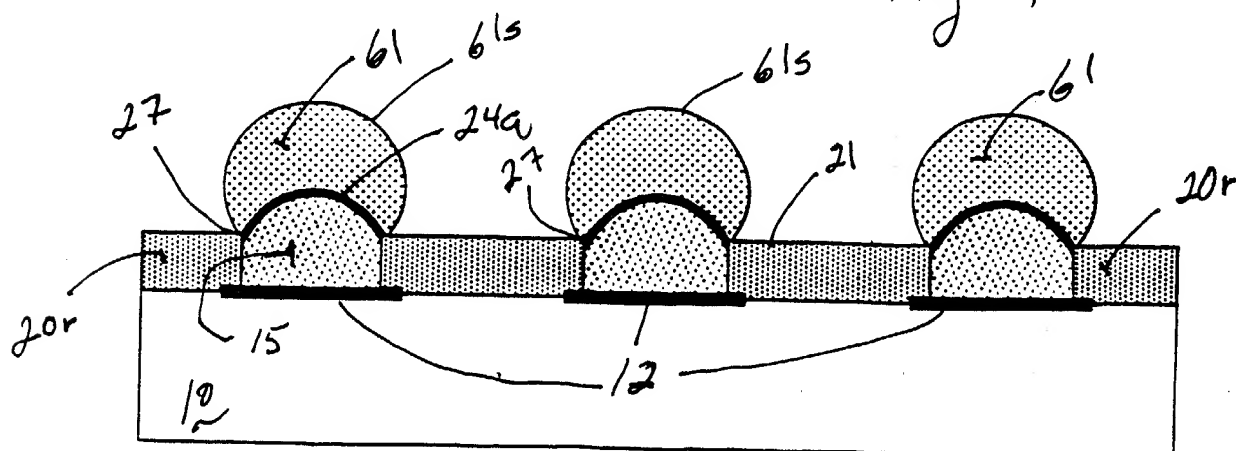
Deposit diffusion barrier

Fig 13



Deposit second kind of solder paste

Fig 14



Reflow wafer to form solder bump
Clean flux residual

Fig 15